

L Number	Hits	Search Text	DB	Time stamp
1	1	("5925898").PN.	USPAT	2003/09/25 10:12
2	12569	((chip or die or led or (light near (emiiter or receiver))) and ((frame or ring) with (substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:30
3	1804	((chip or die or led or (light near (emiiter or receiver))) and ((frame or ring) with (substrate))) and (((frame or ring) and substrate) with (solder or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:32
4	1309	((chip or die or led or (light near (emiiter or receiver))) and ((frame or ring) with (substrate))) and (((frame or ring) and substrate) with (solder or pad))) and (@ad<20010224)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:31
5	1	("4636647").PN.	USPAT	2003/09/25 12:18
6	695	(frame or ring) and ((transparent or light) with substrate) and (solder with (adhesive or paste or bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:26
7	552	((frame or ring) and ((transparent or light) with substrate) and (solder with (adhesive or paste or bond))) and (chip or die or led or (light near (emiiter or receiver)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:31
8	378	((frame or ring) and ((transparent or light) with substrate) and (solder with (adhesive or paste or bond))) and (chip or die or led or (light near (emiiter or receiver)))) and (@ad<20010224)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:32
9	624	((frame or ring) and ((transparent or light) with substrate) and (solder with (adhesive or paste or bond))) and (chip or die or optical or led or (light near (emitter or receiver)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:32
10	431	((frame or ring) and ((transparent or light) with substrate) and (solder with (adhesive or paste or bond))) and (chip or die or optical or led or (light near (emitter or receiver)))) and (@ad<20010224)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:32
11	132	((frame or ring) and ((transparent or light) with substrate) and (solder with (adhesive or paste or bond))) and (chip or die or optical or led or (light near (emitter or receiver)))) and (@ad<20010224)) and ((frame or ring) with (solder or pad or tab or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 12:35